MP Model Code

Base model code

MP defines a sputtering deposition system
(main deposition technology of the equipment, some tools can integrate secondary technology as ebeam deposition or other techniques)



Vacuum level

HV	- high vacuum
Near UHV	- near ultra high vacuum
UHV	- ultra high vacuum

Chamber diameter

Approximate value in millimeters of the main chamber

General geometry

S - defines a configuration in which all chambers have at least a transfer flange in the same plan

Number of chambers

For **S** configuration

-	- 2 in-line chambers
3/4/5	- defines the total number of chambers

Please note that « deposition » concerns only the main technique of the equipment, namely by sputtering. Any other deposition technique is not taken into account in the definition of the model code.

Note also that the Model Code does not define the sample dimension compatibility